

Application No. 09/484,437  
Office Action dated September 20, 2006  
Date of Reply to Office Action: December 20, 2006

Docket No.: M4065.0226/P226

**AMENDMENTS TO THE SPECIFICATION**

Please amend the title as follows:

PREPACKAGED SEMICONDUCTOR DEVICE ASSEMBLY HAVING A PARTIALLY  
CURED ADHESIVE ~~DIE ATTACH CURING METHOD FOR SEMICONDUCTOR DEVICE~~